

**ROCHESTER INSTITUTE OF TECHNOLOGY  
MICROELECTRONIC ENGINEERING**

# VLSI Computer Aided Design (CAD)

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Microelectronic Engineering

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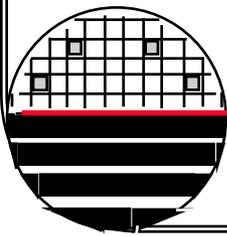
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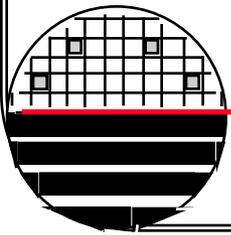
Email: [LFFEEE@rit.edu](mailto:LFFEEE@rit.edu)

MicroE Webpage: <http://www.microe.rit.edu>



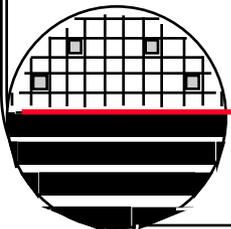
***ADOBE PRESENTER***

This PowerPoint module has been published using Adobe Presenter. Please click on the **Notes** tab in the left panel to read the instructors comments for each slide. Manually advance the slide by clicking on the **play** arrow or pressing the **page down** key.



*OUTLINE*

The Design Process  
Introduction  
Schematic Level Design  
Simulation  
Technology Selection  
Design Rules  
Physical Design  
References  
Homework



## *STAGES IN THE DESIGN PROCESS*

Problem Specification -> Behavioral Design or Truth Table

Logic Design -> Gate Level Schematic

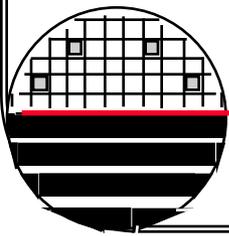
Circuit Design -> Transistor Level Schematic

Simulation -> Output File

Technology Selection -> Design Rules, Layout Layers

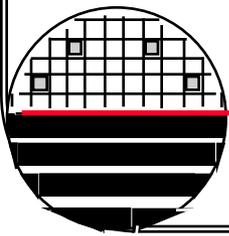
Physical Design -> Layout

Maskmaking – Fabrication – Testing - Packaging



## *INTRODUCTION*

This document is intended to lead the student through a simple digital circuit design with emphasis on the physical design (layout).



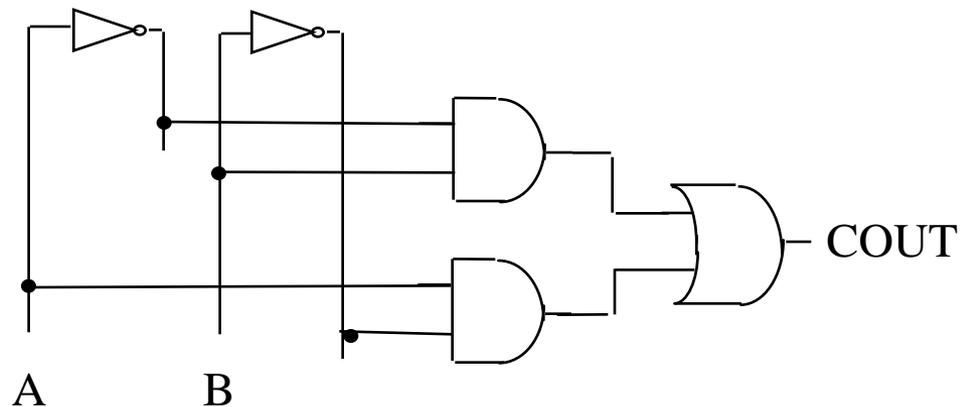
## *EXCLUSIVE OR (XOR) DESIGN EXAMPLE*

Functional Description – This digital logic circuit returns a true (high) value when one of two inputs is high and returns a false (zero) otherwise.

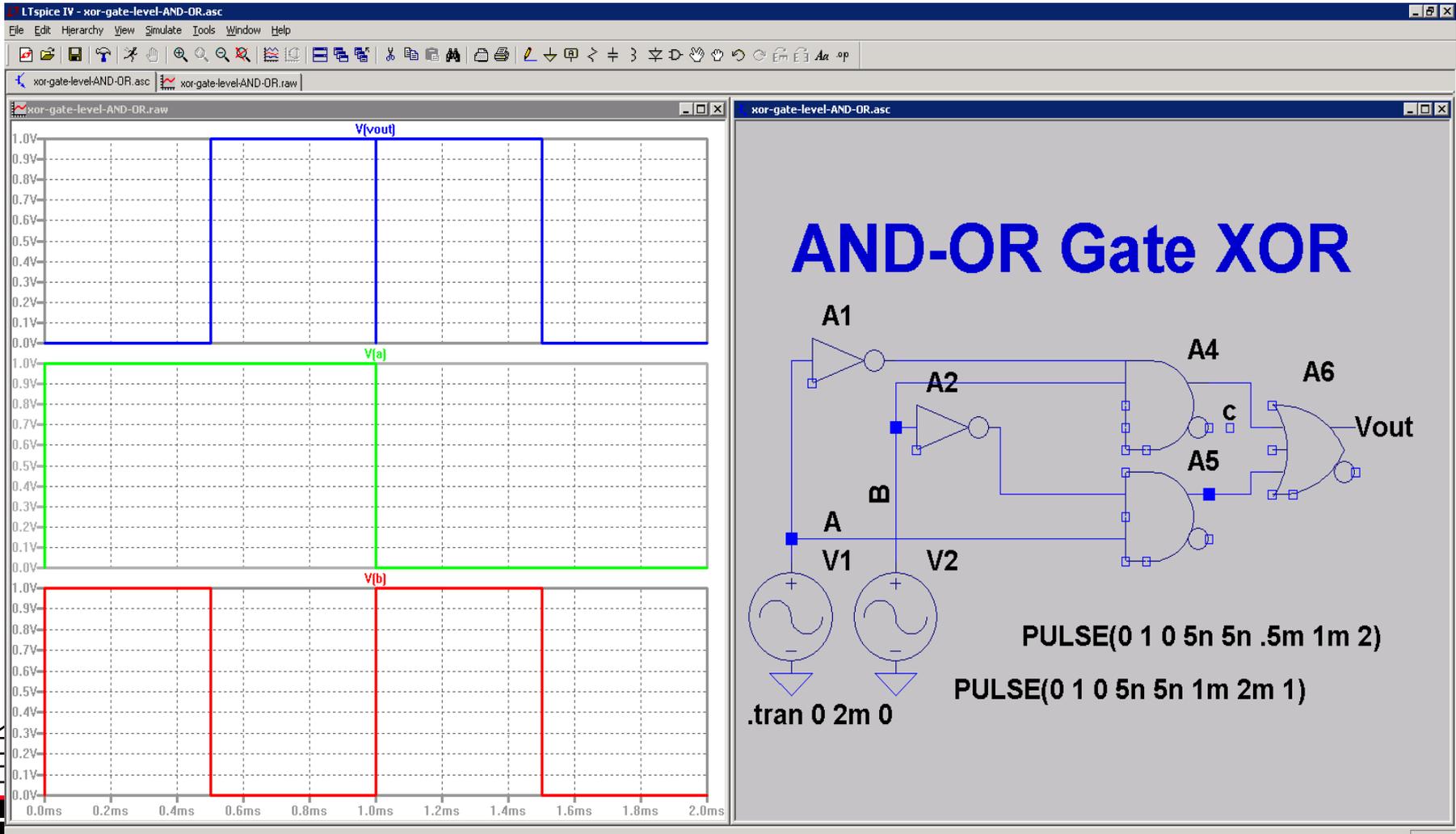
Truth Table

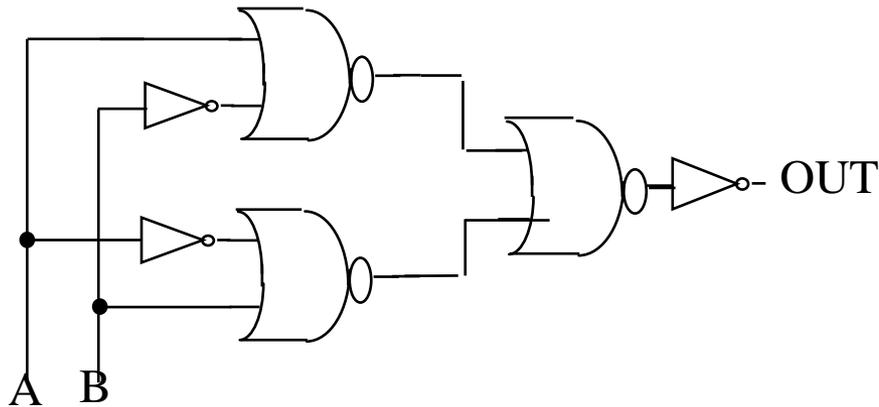
Exclusive OR XOR	VA	VB	VOUT
	0	0	0
	0	1	1
	1	0	1
	1	1	0

Gate Level Design



# GATE LEVEL SIMULATION OF XOR – AND/OR

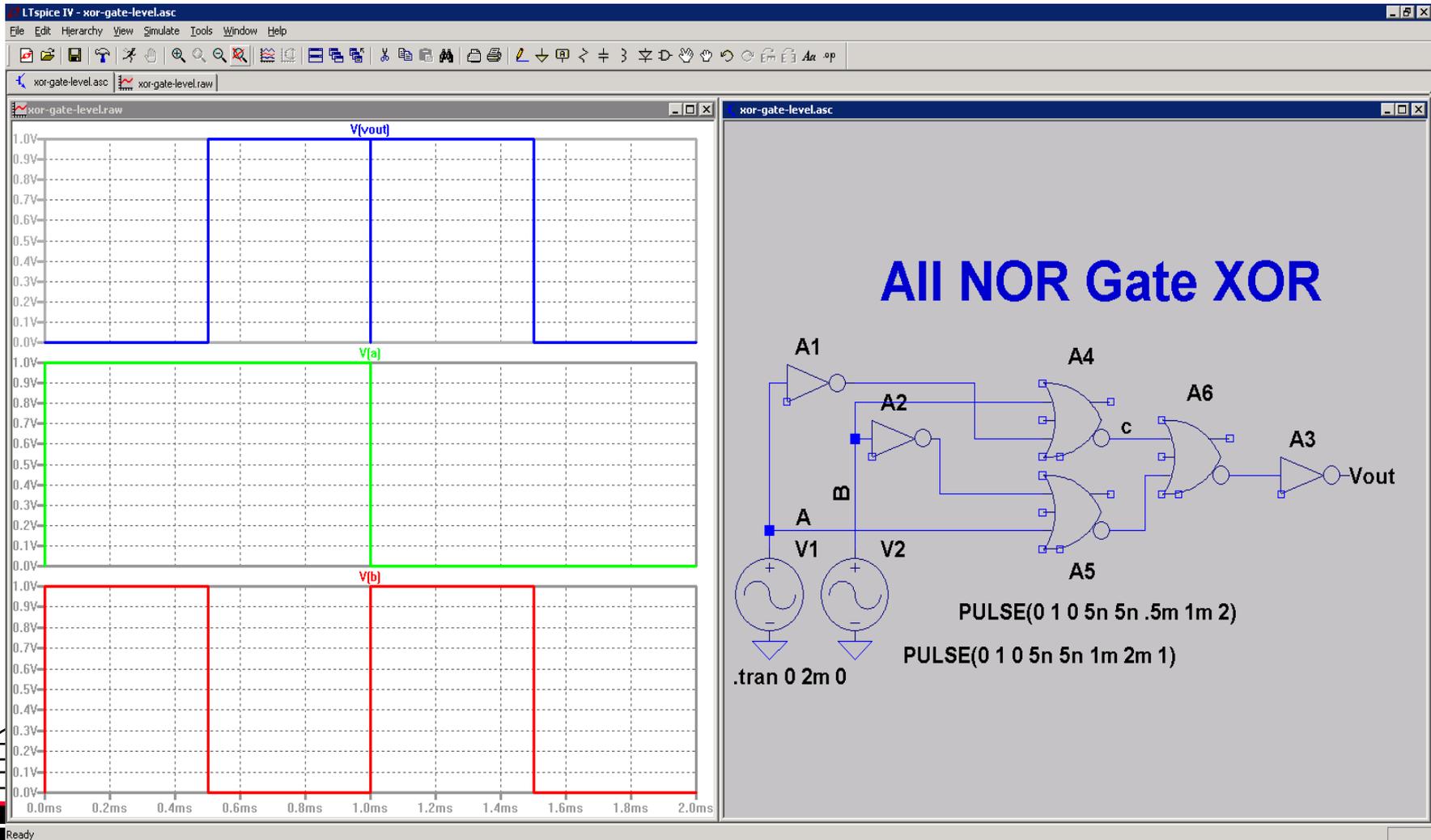


**NOR CIRCUIT REALIZATION FOR XOR**

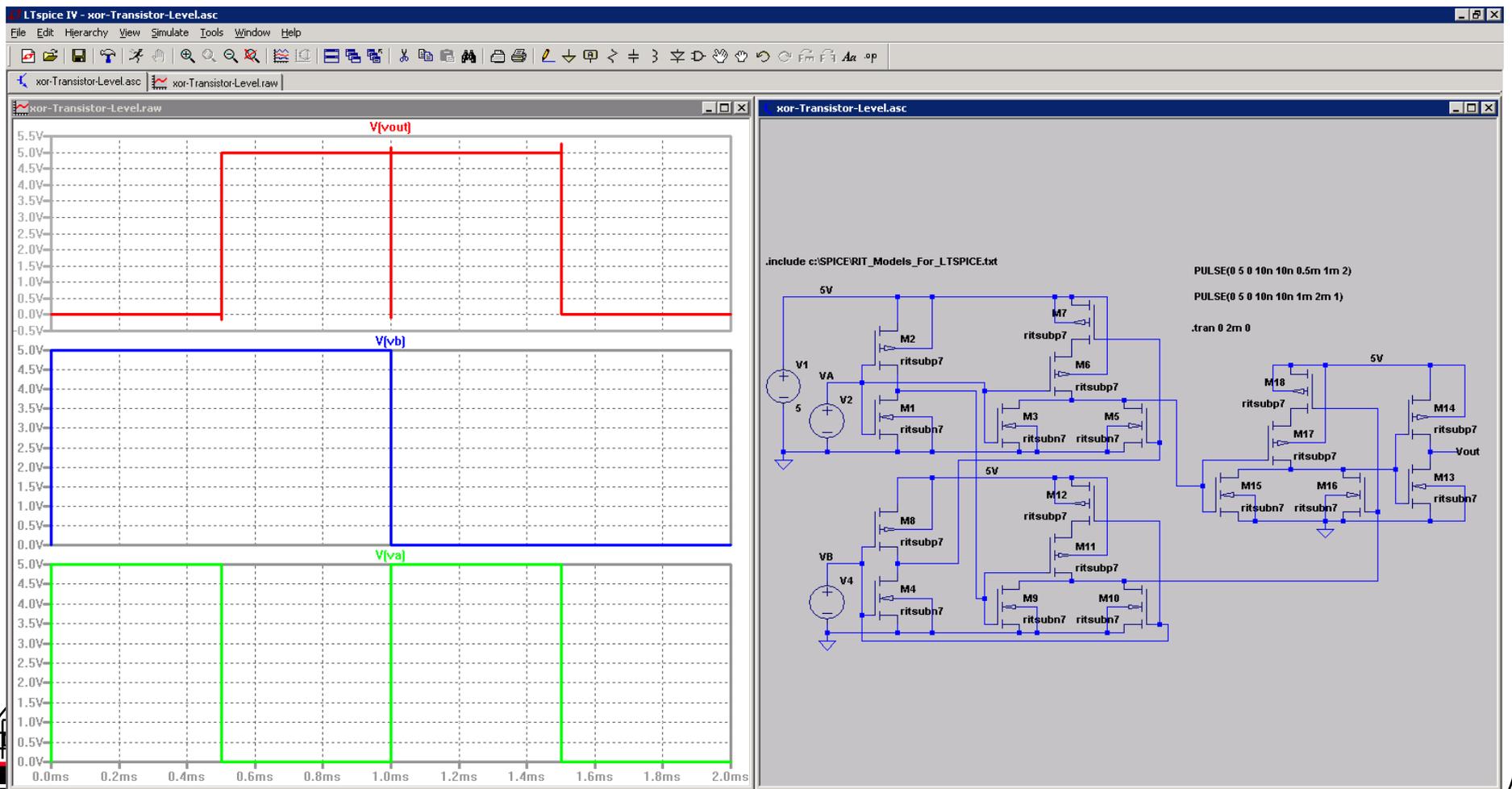
Exclusive OR  
XOR

VA	VB	VOUT
0	0	0
0	1	1
1	0	1
1	1	0

# GATE LEVEL SIMULATION OF XOR – ALL/NOR



## TRANSISTOR LEVEL SIMULATION OF XOR – ALL/NOR



## RIT SUB $\mu$ CMOS – TECHNOLOGY SELECTION

### RIT Sub $\mu$ CMOS

150 mm wafers

$N_{\text{sub}} = 1\text{E}15 \text{ cm}^{-3}$

$N_{\text{n-well}} = 3\text{E}16 \text{ cm}^{-3}$

$X_j = 2.5 \mu\text{m}$

$N_{\text{p-well}} = 1\text{E}16 \text{ cm}^{-3}$

$X_j = 3.0 \mu\text{m}$

LOCOS

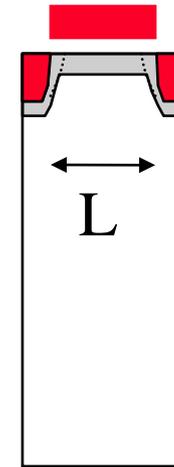
Field  $O_x = 6000 \text{ \AA}$

$X_{ox} = 150 \text{ \AA}$

$L_{\text{min}} = 1.0 \mu\text{m}$

LDD/Side Wall Spacers

2 Layers Aluminum



Long  
Channel  
Behavior

3.3 Volt Technology

$V_T$ 's = +/- 0.75 Volt

Robust Process (always works)

Fully Characterized (SPICE)

***MOSIS TSMC 0.35 2-POLY 4-METAL LAYERS***

<b>MASK LAYER NAME</b>	<b>MENTOR NAME</b>	<b>GDS #</b>	<b>COMMENT</b>
<b>N WELL</b>	<b>N_well.i</b>	<b>42</b>	
<b>ACTIVE</b>	<b>Active.i</b>	<b>43</b>	
<b>POLY</b>	<b>Poly.i</b>	<b>46</b>	
<b>N PLUS</b>	<b>N_plus_select.i</b>	<b>45</b>	
<b>P PLUS</b>	<b>P_plus_select.i</b>	<b>44</b>	
<b>CONTACT</b>	<b>Contact.i</b>	<b>25</b>	<b>Active_contact.i 48</b> <b>poly_contact.i 47</b>
<b>METAL1</b>	<b>Metal1.i</b>	<b>49</b>	
<b>VIA</b>	<b>Via.i</b>	<b>50</b>	
<b>METAL2</b>	<b>Metal2.i</b>	<b>51</b>	
<b>VIA2</b>	<b>Via2.i</b>	<b>61</b>	<b>Under Bump Metal</b>
<b>METAL3</b>	<b>Metal3.i</b>	<b>62</b>	<b>Solder Bump</b>

These are the main design layers up through metal two

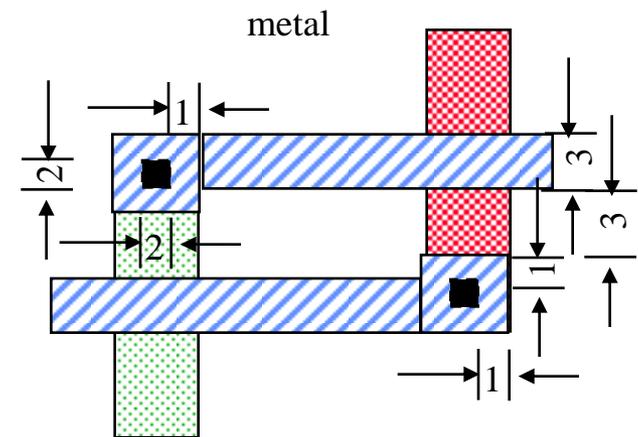
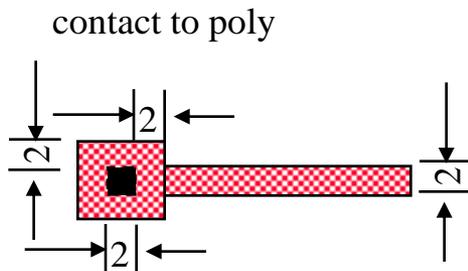
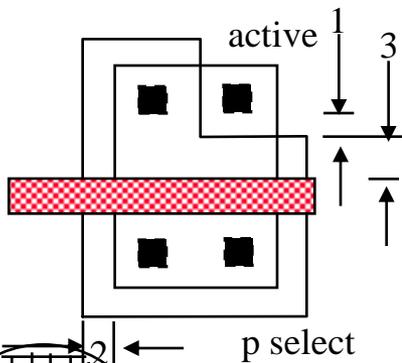
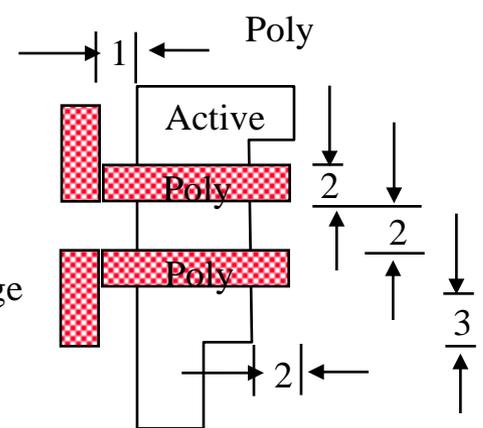
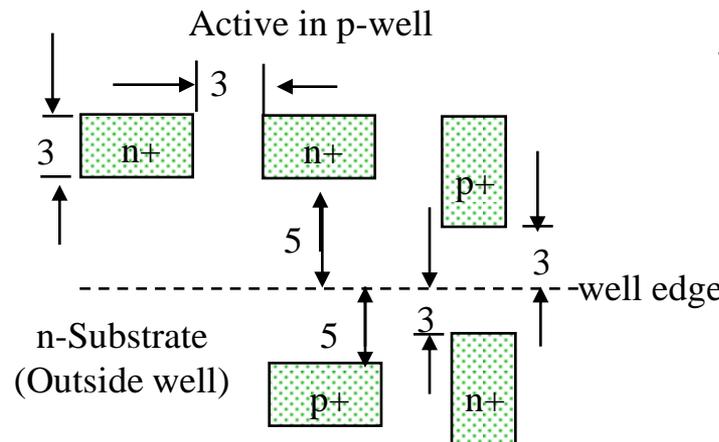
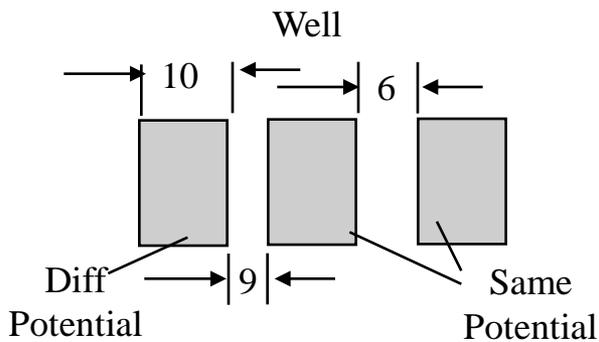
## ***MORE LAYERS USED IN MASK MAKING***

<b>LAYER</b>	<b>NAME</b>	<b>GDS</b>	<b>COMMENT</b>
	<b>cell_outline.i</b>	<b>70</b>	<b>Not used</b>
	<b>alignment</b>	<b>81</b>	<b>Placed on first level mask</b>
	<b>nw_res</b>	<b>82</b>	<b>Placed on nwell level mask</b>
	<b>active_lettering</b>	<b>83</b>	<b>Placed on active mask</b>
	<b>channel_stop</b>	<b>84</b>	<b>Overlay/Resolution for Stop Mask</b>
	<b>pmos_vt</b>	<b>85</b>	<b>Overlay/Resolution for Vt Mask</b>
	<b>LDD</b>	<b>86</b>	<b>Overlay/Resolution for LDD Masks</b>
	<b>p plus</b>	<b>87</b>	<b>Overlay/Resolution for P+ Mask</b>
	<b>n plus</b>	<b>88</b>	<b>Overlay/Resolution for N+ Mask</b>
	<b>tile_exclusion</b>	<b>89</b>	<b>Areas for no STI tiling</b>

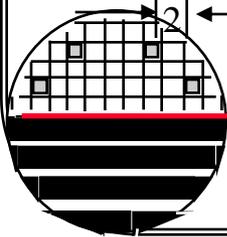
These are the additional layers used in layout and mask making

# MOSIS LAMBDA BASED DESIGN RULES

<http://www.mosis.com/design/rules/>



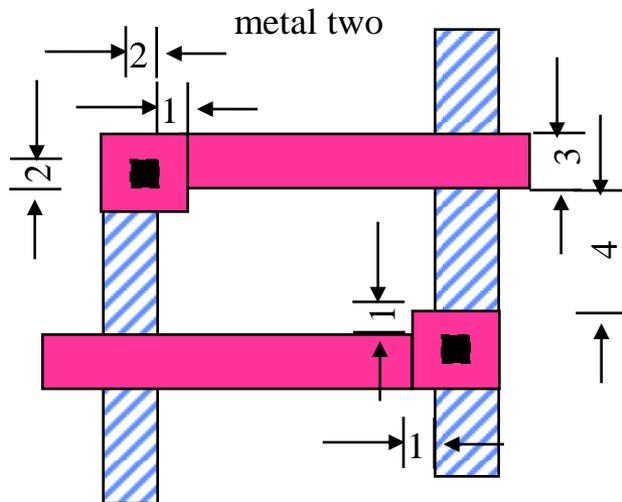
If  $\lambda = 1 \mu\text{m}$  then contact is  $2 \mu\text{m} \times 2 \mu\text{m}$



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# MOSIS LAMBDA BASED DESIGN RULES

<http://www.mosis.com/design/rules/>



MOSIS Educational Program

Instructional Processes Include:

AMI  $\lambda = 0.8 \mu\text{m}$  SCMOS Rules

AMI  $\lambda = 0.35 \mu\text{m}$  SCMOS Rules

Research Processes:

go down to poly length of 65nm

## *GETTING STARTED WITH LAYOUT EDITOR IC*

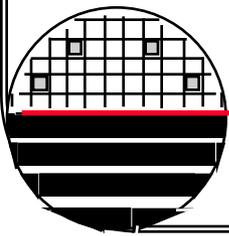
Usually the workstation screen will be blank, move the mouse to view a login window.

Login: **username**

Password: **\*\*\*\*\***

The screen background will change and your desktop will appear. On the top of the screen click on **Applications** then **System Tools** then **Terminal**. A window will appear that has a Unix prompt inside. Type the command **ls** at the prompt to see a list of directories and files, the account should be empty.

Type **ic <ENTER>**, it will take a few seconds, then maximize the IC Station window by clicking the left mouse button on the large square in the upper right corner of the IC Station window.



## *SHARED FOLDERS*

We have set up a shared folder for this course that has primitive cells which you can open and copy from for your designs.

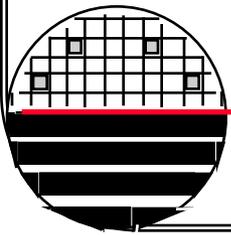
***/shared/mcee550/***

Students and faculty for this course have their own personal accounts where they can keep their designs.

***/home/username/filename/***

All users have access to some public folders that have files for processes, design rules, etc.

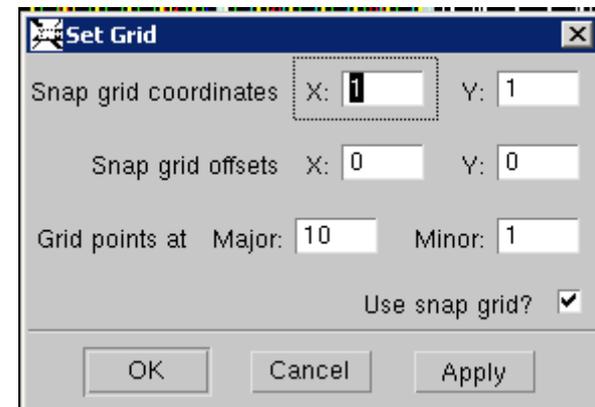
***/tools/ritpub/process/fuller***



## *STARTING A STANDARD CELL DESIGN*

On the right hand panel of the IC Station window click on **Create** to open the create Cell window. Fill in a cell name that includes your initials (so I can identify your cells from other students cells). For process browse to or type **/tools/ritpub/process/fuller**. This will select the correct level names, level numbers and colors for the TSMC 0.35 2P3M process as discussed above. The workspace should change to a black screen with dots. If you move the cursor around you can find different xy cursor locations as displayed at the top-center.

On top banner select **Other>Window>Set Grid**

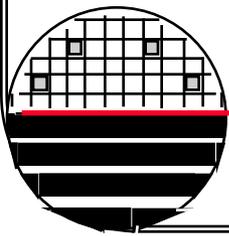


## *STARTING A STANDARD CELL DESIGN*

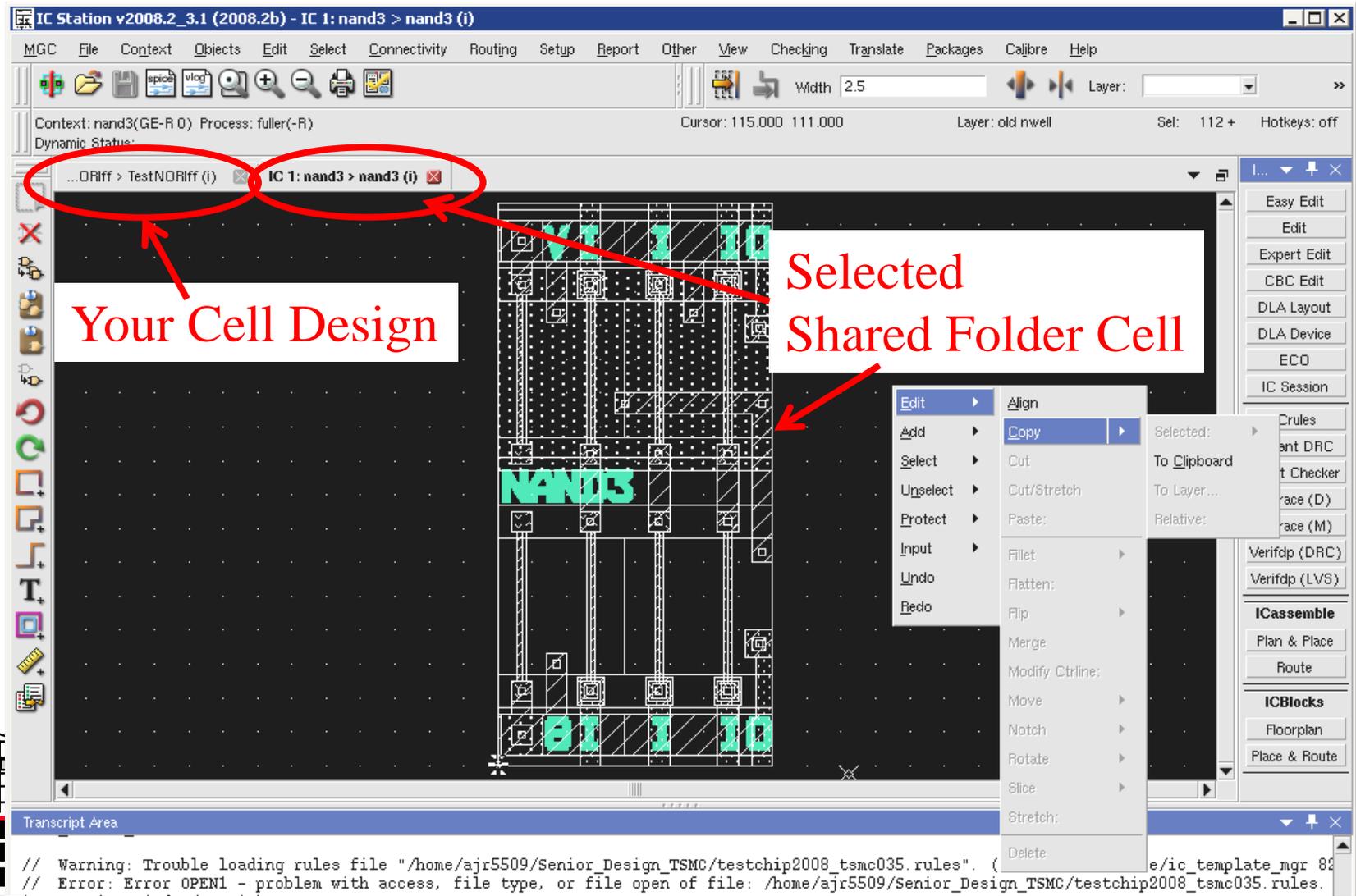
Open a cell from the shared folder by clicking on the open cell icon in the top-left banner. Navigate to **/shared/mcee550/** and select the cell you want in your design. Press **Shift+F8** to scale the window to fit the cell. Drag a box around the cell to select it and right click to **Edit>Copy>ToClipboard**

Then return to your cell and right click and **Edit>Paste**. Place the lower left corner where you want the cell. **Shift+F8** will scale the window to fit the cell. **F2** will unselect cell.

If you use the add cell approach to build your design you can place a cell from **/shared/mcee500** folder in your design. To see the details inside the cell type anywhere in the workspace **Peek** then **OK**.



# COPYING CELL FROM SHARED FOLDER



## PASTING PRIMITIVE CELLS INTO YOUR CELL DESIGN

The screenshot displays the IC Station software interface. The title bar reads "IC Station v2008.2\_3.1 (2008.2b) - IC 0: TestNORliff > TestNORliff (i)". The menu bar includes MGC, File, Context, Objects, Edit, Select, Connectivity, Routing, Setup, Report, Other, View, Checking, Translate, Packages, Calibre, and Help. The toolbar contains icons for file operations, zooming, and editing. The status bar shows "Context: TestNORliff(GE-E 0) Process: fuller(-R)", "Cursor: 390.000 120.000", "Layer: Metal2.i", "Sel: 0 +", and "Hotkeys: off".

The main workspace shows a grid-based layout with several primitive cells pasted into it. The cells are labeled "INV", "NOR2", and "NULL". The layout is organized into a grid with vertical and horizontal lines. The cells are arranged in a pattern that suggests a logic circuit implementation. The "INV" cells are arranged in a row, followed by "NOR2" cells, and "NULL" cells at the ends. The grid is overlaid with a pattern of colored lines (green, blue, red, yellow) representing different layers or routing paths.

On the right side, there is a "Back" button and an "Add Objects" menu with options: Shape \*, Path \*, Text \*, Multi Text, Property \*, Prop Text \*, Cell \*, Device \*, Via, Panel \*, Ruler \*. Below this is an "Edit" menu with options: Copy \*, Rel Copy, Move \*, Rel Move, Align, Rotate \*, Flip \*, Notch \*, Modify \*, Stretch \*, Rel Stretch, and Cut/Stretch \*.

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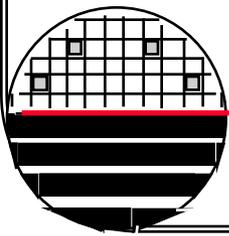
## *INTERCONNECTING PRIMITIVE CELLS*

The primitive cells are interconnected using Metal-1 and Metal-2 in the routing channels above and below the primitive cells. First place horizontal metal lines in the routing channels by creating a shape with the following command (type anywhere in the drawing window)

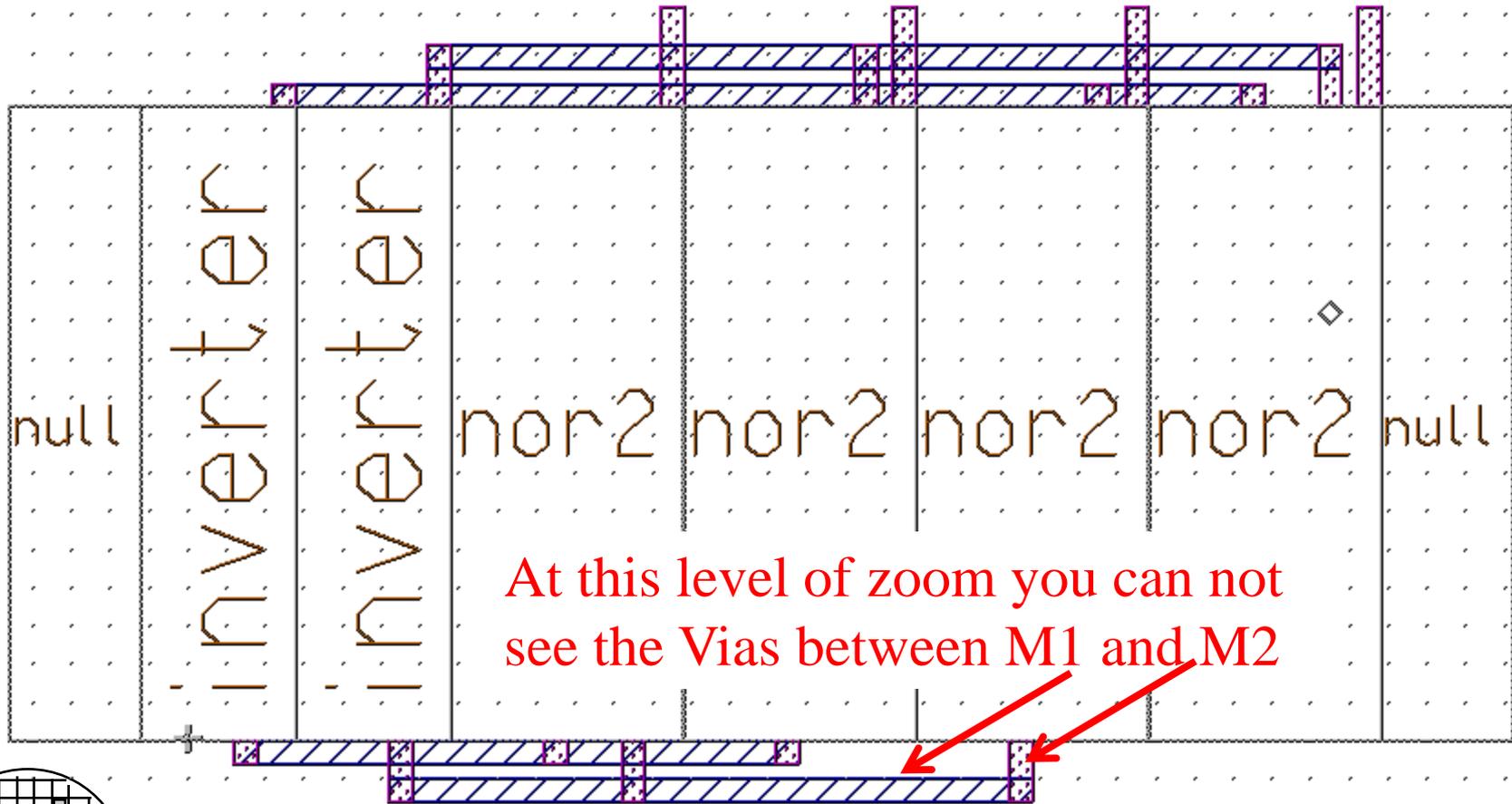
**`$add_shape([[0,166],[368,172]],49)`**

This will draw a box with lower left corner at  $x=0$ ,  $y=166$  and upper right corner at  $x=368\mu\text{m}$ ,  $y=172\mu\text{m}$ , with layer number 49 (metal-1). This should be a horizontal metal-1 interconnect line at the top of your cell if you placed the lower left corner of your cell at  $(0,0)$

Both M1 and M2 will need some type of contact cut or Via. See next page for examples

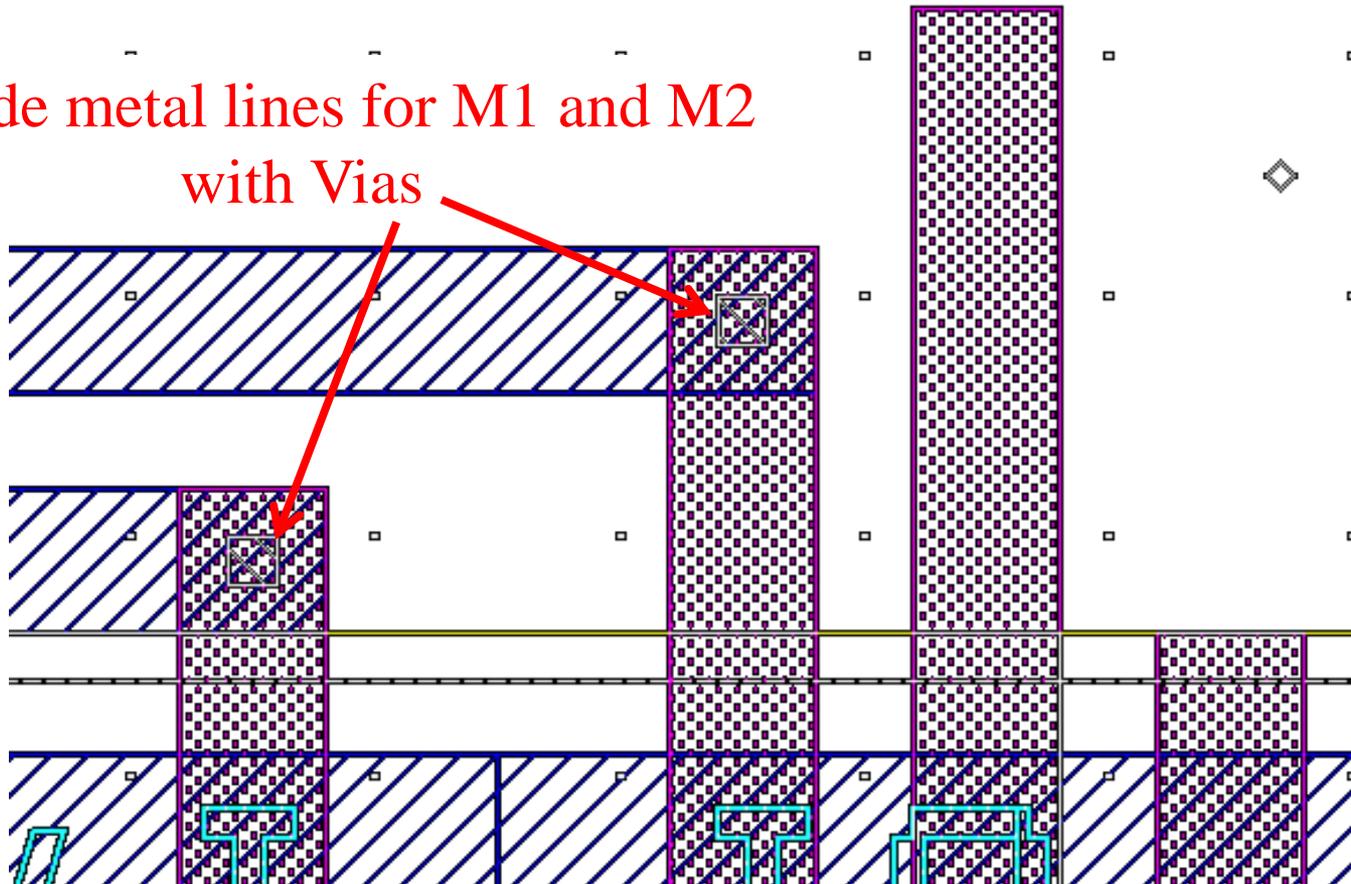


# M1 AND M2 INTERCONNECTS



# CONNECTIONS BETWEEN M1 AND M2

6 $\mu$ m wide metal lines for M1 and M2  
with Vias

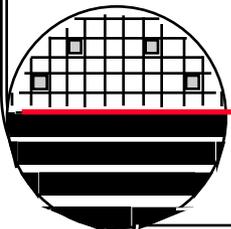
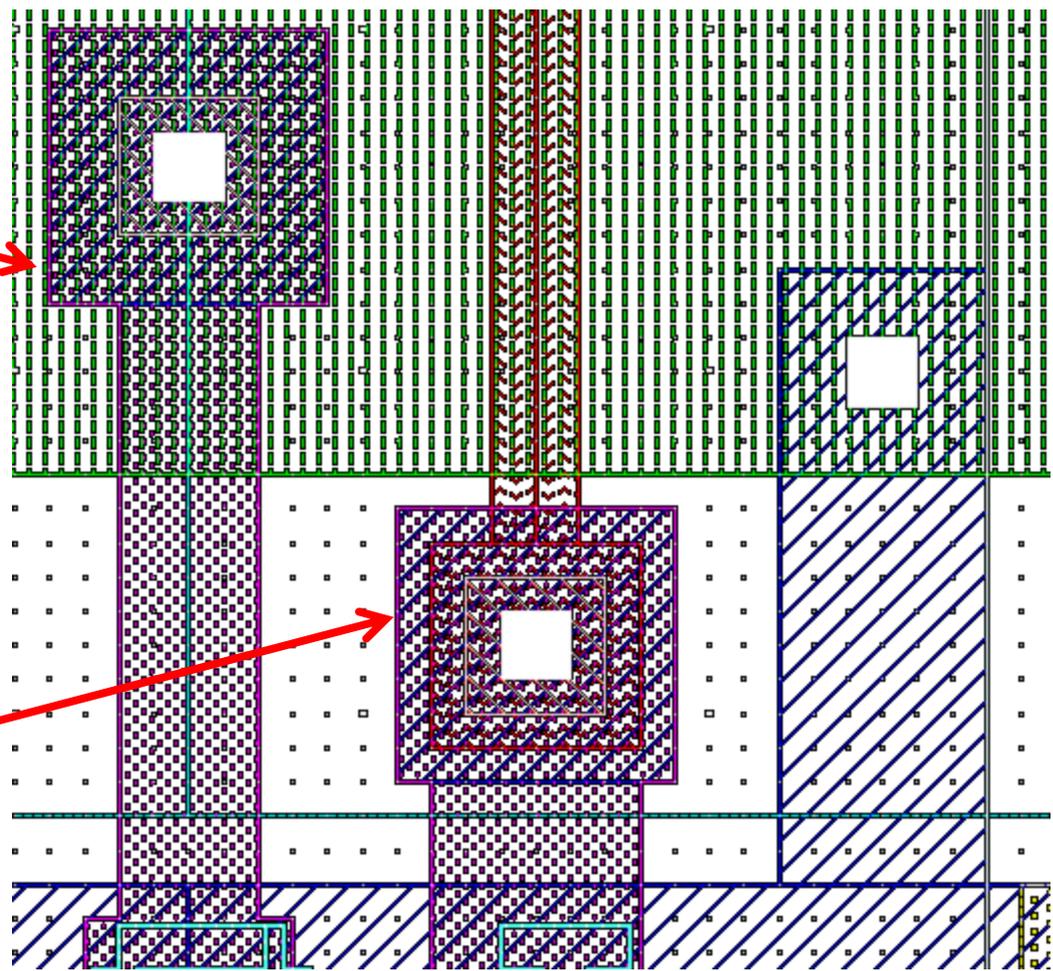
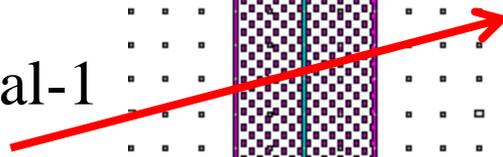


**CONNECTIONS TO ACTIVE AND POLY**

Metal-2 to Via to Metal-1  
to CC to Active



Metal-2 to Via to Metal-1  
to CC to Poly



## *USING THE VLSI LAB WORKSTATIONS AND MENTOR GRAPHICS CAD TOOLS*

Usually the workstation screen will be blank, press any key to view a login window. Login or switch user and then login.

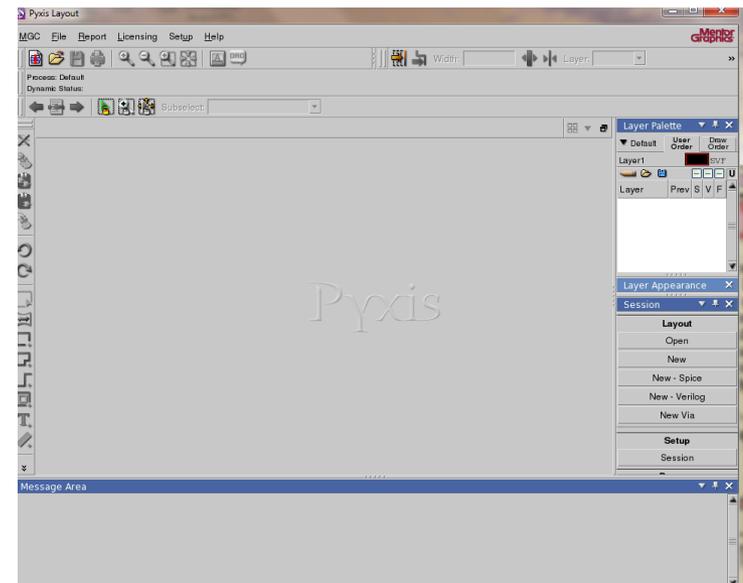
Login: username (RIT computer account)

Password: \*\*\*\*\*

The screen background will change and your desktop will appear. On the top of the screen click on **Applications** then **System Tools** then **Terminal**. A window will appear that has a Unix prompt inside. Type the command **ls** at the prompt to see a list of your directories and files.

Type **ic** <RET>, it will take a few seconds, then the Pyxis Layout user interface will appear.

Maximize the Pyxis Layout window.



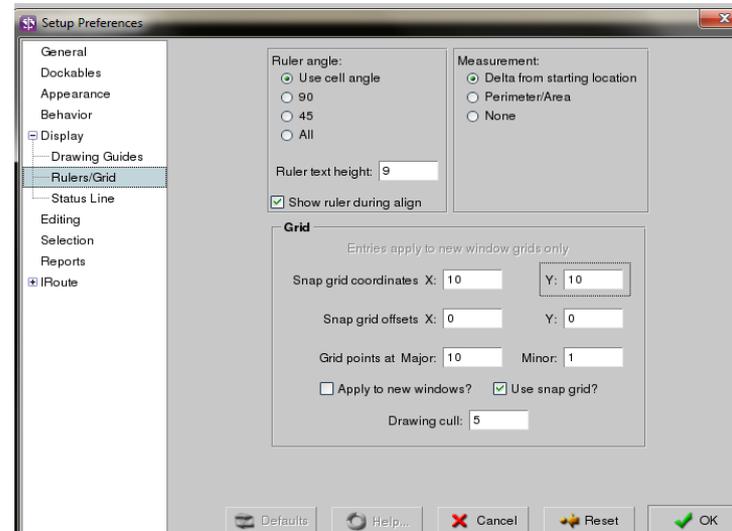
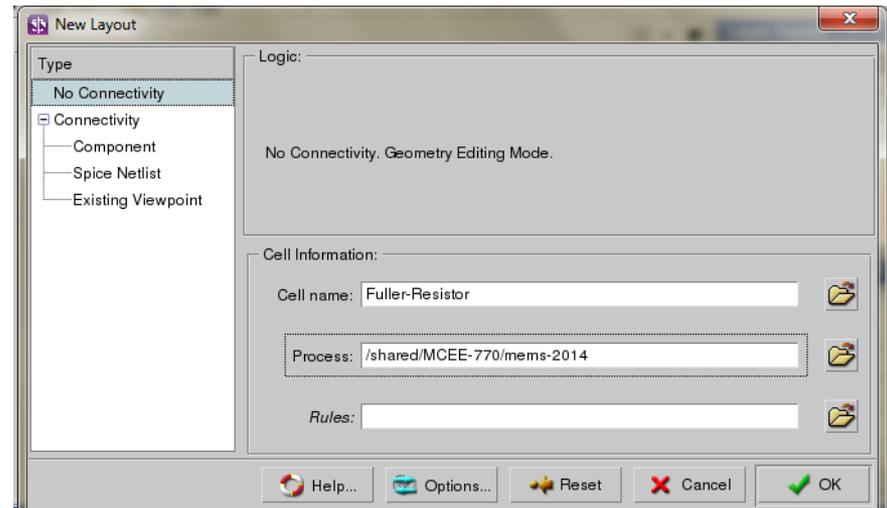
# USING THE HP WORKSTATIONS AND MENTOR GRAPHICS CAD TOOLS - PROCESS AND GRID

In the session menu palette on the right hand side of the screen, under Layout, select **New**, using the left mouse button. For cell name type **name-device**. Set the process by typing **/tools/ritpub/process/mems-2014** in the process field. Leave the Rules field blank. Click **OK**

At the top left of the window check that the process is **mems-2014** not Default. If not correct go to top banner click on **Context>Process>Set Process**

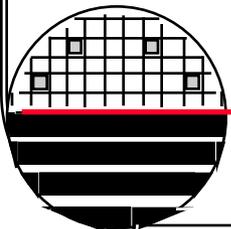
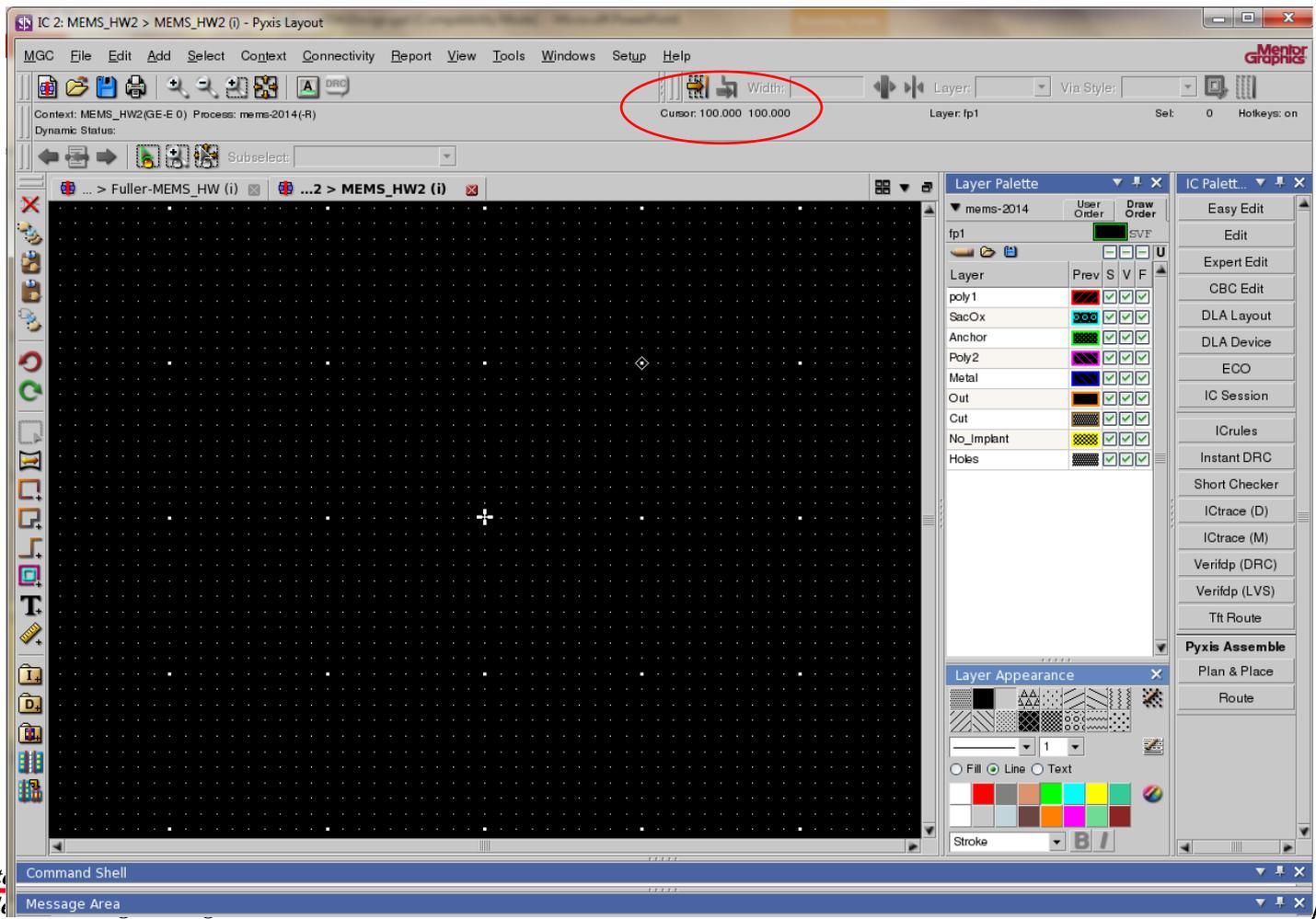
The Layer Palette should show the layers you expect to used for your device layout.

On top banner select **Setup>Preferences>Display>Rulers/Grid**  
Set Snap to **10** and **10** as shown. (or other values as necessary)



## USING THE HP WORKSTATIONS AND MENTOR GRAPHICS CAD TOOLS – WORKSPACE, LOCATION

The plus mark + is (0,0) the small dots are the 10 um grid the large dots are the 100um grid. The mouse cursor is shown by the diamond and is at (100um,100um) as indicated by the cursor position at the top of the workspace.



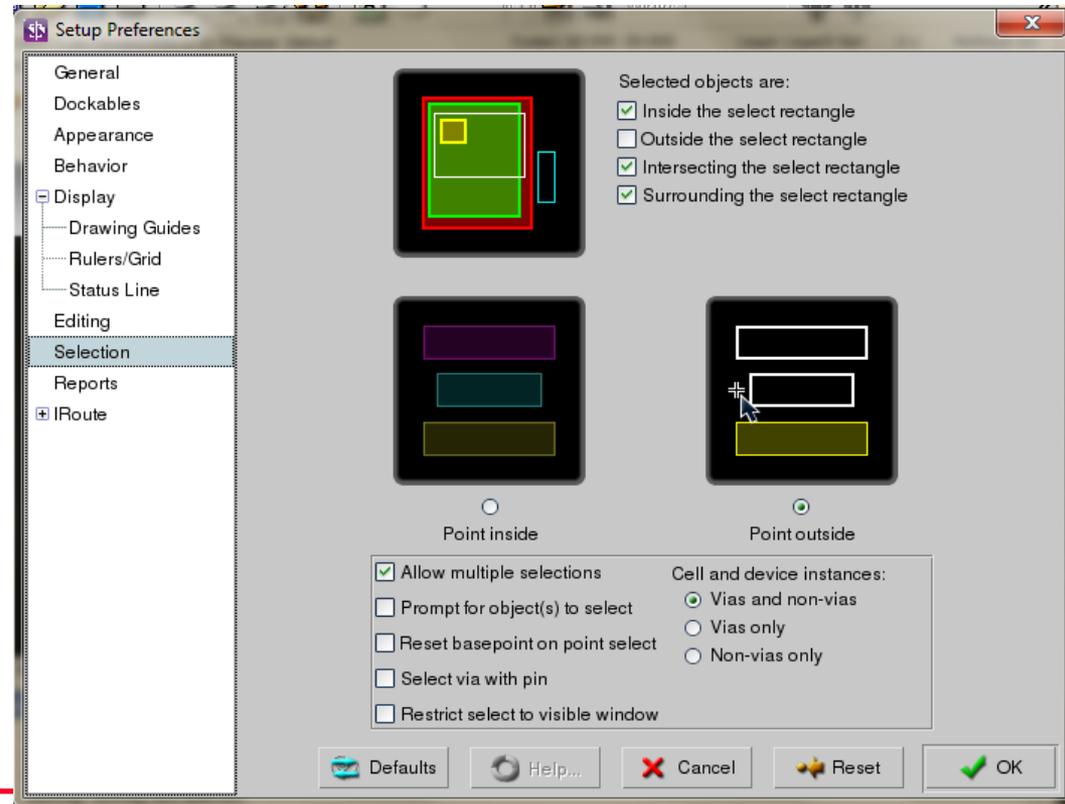
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Microelectronics

# USING THE HP WORKSTATIONS AND MENTOR GRAPHICS CAD TOOLS – SELECTING OBJECTS

Select easy edit, Select Shape. Draw boxes by click and drag of mouse. Unselect by pressing **F2** function key. The highlighted layer in the layer palette is selected prior to drawing. Unselect by pressing **F2**. Exit drawing by pressing **ESC**.

Selecting multiple objects is defined in **Setup>Selection**

Unclick **Surrounding** the select rectangle to not select the cell outline



## ***DRAWING BOXES AND OTHER SHAPES***

Select easy edit, right click and select Show Scroll Bars, scroll through the various edit commands.

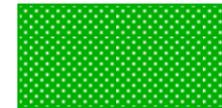
**DRAW BOXES** by click and drag of mouse. Unselect by pressing F2 function key. The following command will draw a 3000  $\mu\text{m}$  by 3000  $\mu\text{m}$  box with layer 4 color/shading. Put the cursor in the workspace and start typing. A text line window will pop up. If the command has a typo just start typing again and use the up arrow to recall previous text.

```
$add_shape([[0,0],[3000,3000]],4)
```

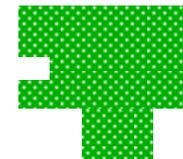
Location of lower  
left corner

Location of upper  
right corner

Box Color



The Notch command is useful to change the size of a selected box or alter rectangular shapes into more complex shapes.

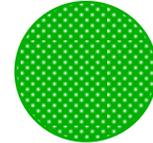


## DRAWING CIRCLES

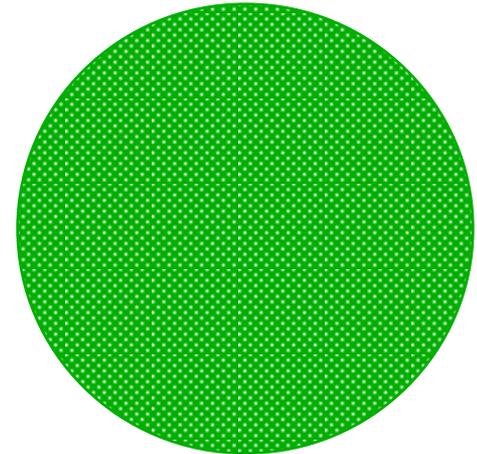
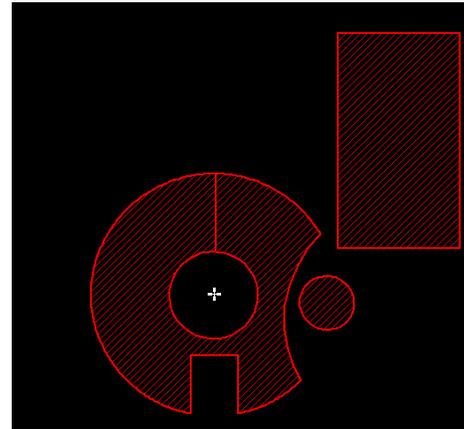
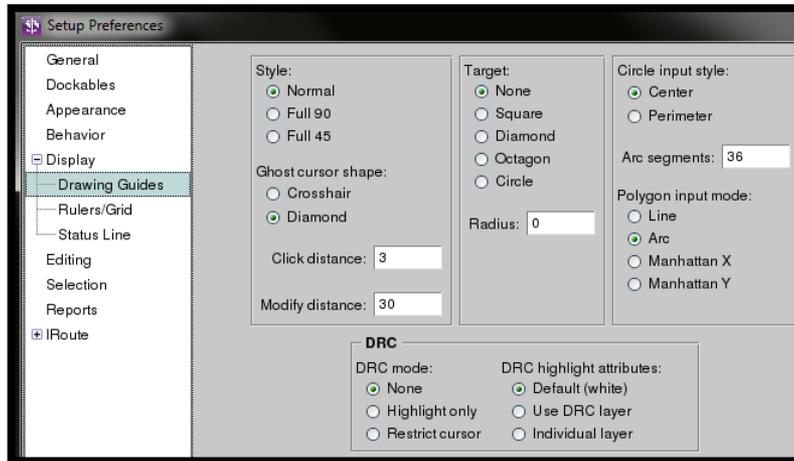
**DRAW CIRCLES** by typing `$set_location_mode(@arc)` return. The following command will draw a 100 $\mu$ m radius circle centered at (0,0) using 300 straight line segments.

`$add_shape($get_circle([0,0],[100,0],300),3)`

To reset to rectangles type `$set_location_mode(@line)` return.



**MOVE, COPY, DELETE, NOTCH, etc:** Selected objects will appear to have a bright outline. Selected objects can be moved (**Move**), copied (**Copy**), deleted (**Del**), notched (**Notc**). When done **unselect** objects, press F2.



**Change an Object to another layer:** Selected object(s) click on **Edit** on the top banner, select **Change Attributes**, change **layer name** to the name you want. When done press **F2** to unselect

## *USING THE HP WORKSTATIONS AND MENTOR GRAPHICS CAD TOOLS - OTHER*

**ZOOM IN OUT:** pressing the + or - sign on right key pad will zoom in or out. Also pressing **shift + F8** will zoom so that all objects are in the view area. Select **View** then **Area** and click and drag a rectangle will zoom so that the objects in the rectangle are in the view area.

**MOVING VIEW CENTER:** pressing the middle mouse button will center the view around the pointer.\

**ADDING TEXT:** **Add > Polygon Text** click on layout where you want it located. Select the text box and **Edit > Change > Attributes**, change pgttext, change scale to 3.0

**SCREEN PRINT:** Click on **MGC** and select **Capture Screen**. Enter file name and location such as **Lynn.png** and **Desktop**. After saving you can use a flash drive and transfer the file to another computer.

**LOG OUT:** upper right of screen click on name and select **LOG OUT**

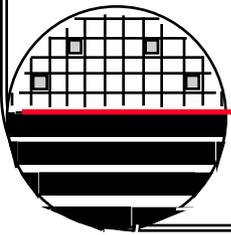
## ***BASIC UNIX COMMANDS***

### **Command**

### **Description**

ls	list the files and directories in the current directory
cd	change directory
cd ..	go up one directory
mv	move a file (rename a file)
rm	remove a file (delete a file)
pwd	display path of current directory
mkdir	create a new directory
rmdir	remove a directory
yppasswd	change your password

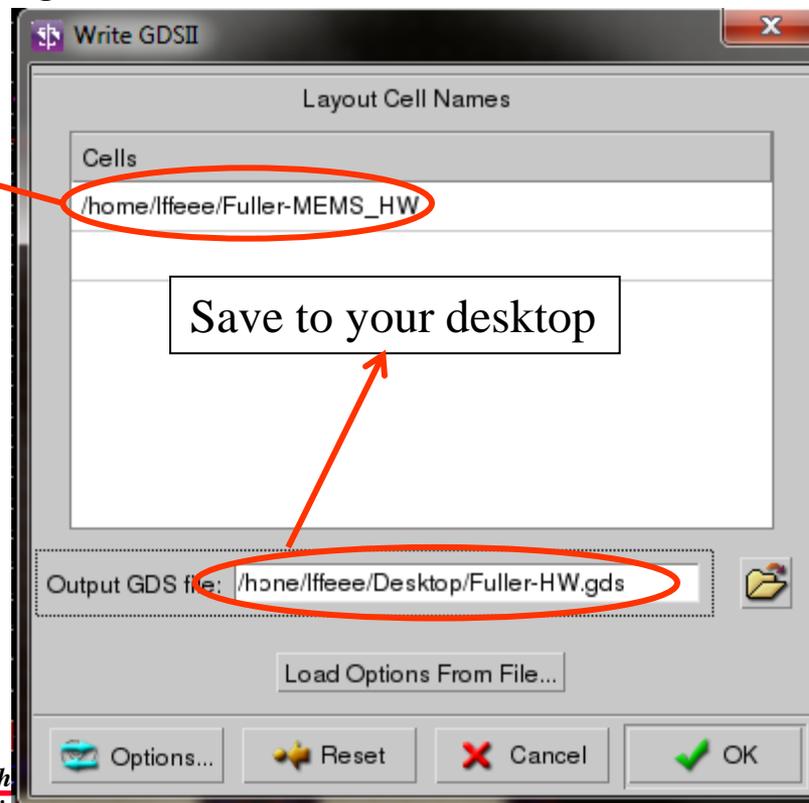
It is important to remember that since this is a UNIX operating system, the commands are case sensitive.



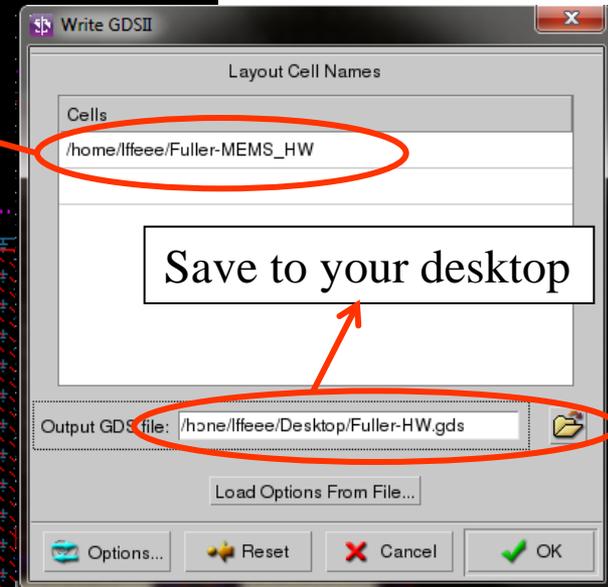
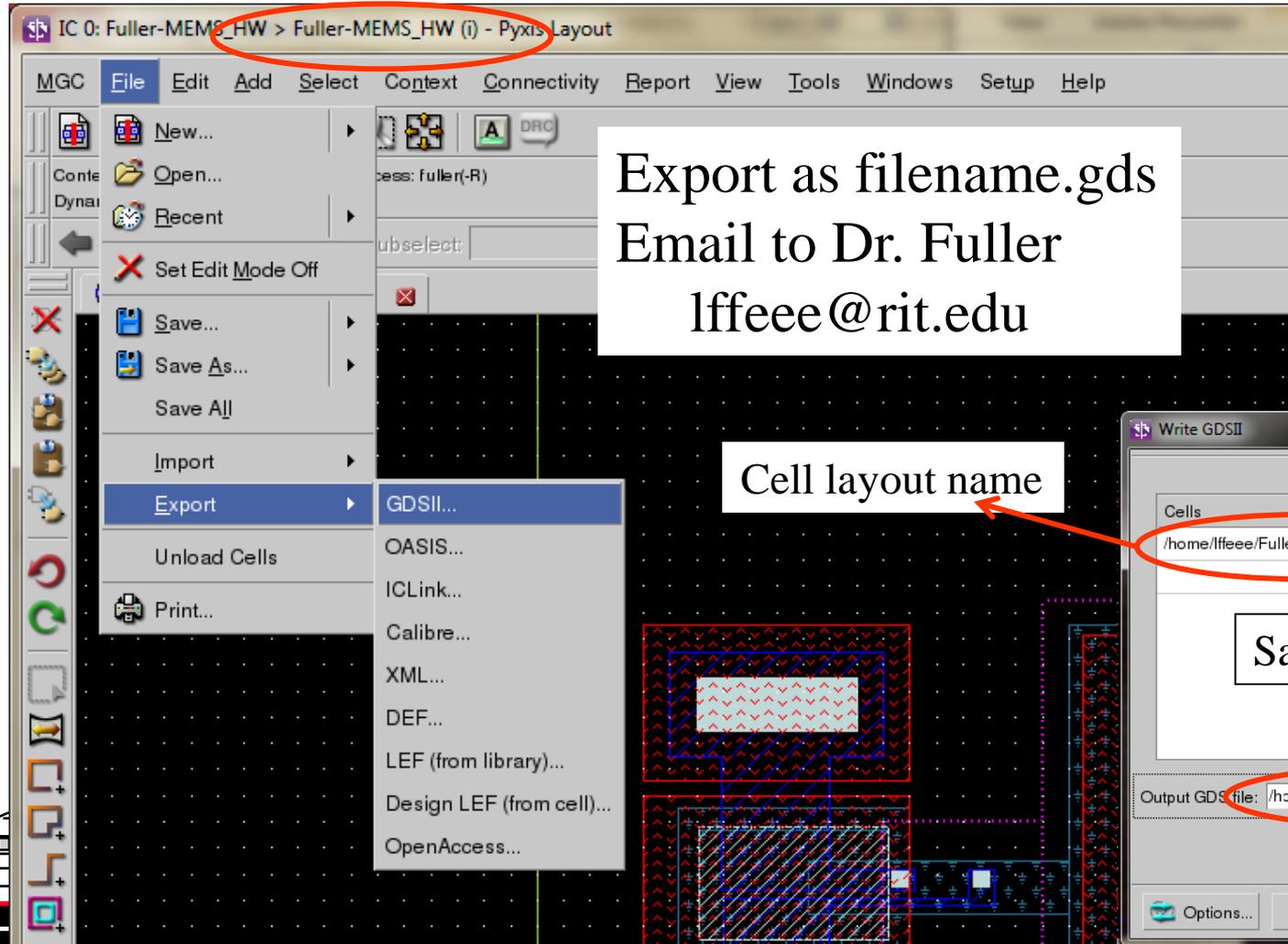
## GDS FILE GENERATION

Once the cell design is completed export the GDS file for maskmaking. Select **Translate** on the top banner and then **Write GDSII** Output file needs full path name and .gds extension.

Cell layout name



# EXPORT CELL DESIGN AS GDS II FILE



# MASK ORDER FORM

**Rochester Institute of Technology**  
**Semiconductor & Microsystems Fabrication Laboratory**

Maskmaking  
 Order Request

Name  
 Company  
 Department  
 Street Address  
 City, State and Zip Code  
 Phone Number  
 SMFL Project Code  
 Email Address

Order Date  
 Order Due Date

Dr Fuller  
RIT

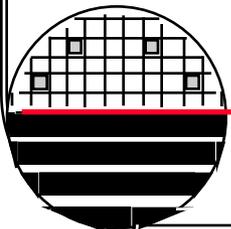
Design File Name (.gds)	mems-2014-final.gds
Number of Mask Levels to be Written	7
Cell Layout Size	16.5mm x 16.5mm
Name of Cell in Design File to be used	mems-2014-final

Mask Type Needed			
<input type="checkbox"/> Contact Aligner	Defaults	Scale:	1X
• Max field size - 105mm x 105mm		Mask Size:	5" x 5" x 0.09" Soda Lime
		Orientation:	Mirror 90
		Fracture Resolution:	0.5um
<input type="checkbox"/> GCA Stepper	Defaults	Scale:	5X
• Max field size - 20mm x 20mm		Mask Size:	5" x 5" x 0.09" Soda Lime
		Orientation:	Mirror 135
		Fracture Resolution:	0.5um
<input checked="" type="checkbox"/> ASML Stepper	Defaults	Scale:	5X
Max field size - 22mm x 22mm		Mask Size:	6" x 6" x 0.12" Quartz
		Orientation:	Mirror 90
		Fracture Resolution:	0.5um

<b>Single Field Array Plate</b>		<input type="checkbox"/> Yes
		<input type="checkbox"/> Array with _____ columns (x) and _____ rows (y)
Array element size	X: _____ um	Y: _____ um

**Notes:**  
 If multiple design files are to be incorporated into your array - please specify the array layout separately  
 Your designs will be butted together to form the array unless otherwise specified

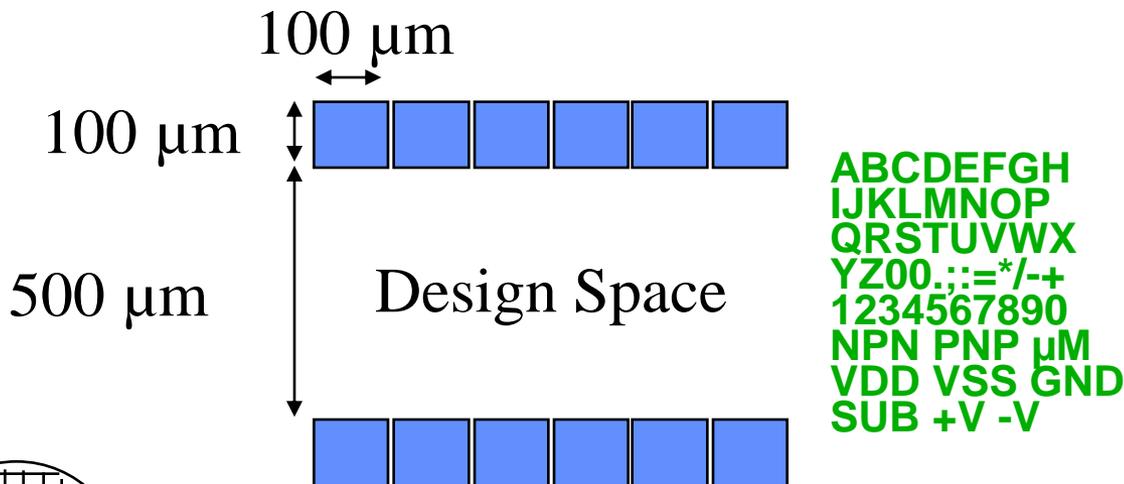
<b>Multiple Field Array Plate</b>		<input type="checkbox"/> Yes
Numbers of Levels on Plate	_____	
Please specify which levels are to be grouped together on which plate on the Details Sheet		



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## ADDING PAD CELL AND LETTERS

From the banner at the top of the page choose **Objects>add>cell**. A tan pop-up window will appear at the bottom of the page. Type in the following cell name, all lower case, **/tools/ritpub/padframes/ritpmos/ritpmos\_12\_pads** and click the left mouse button on the location button. Then position the cursor at the origin 0,0 and click the left mouse button. Click the left mouse button on the cancel button on the tan pop-up box. Press SHIFT and F8 to View All. You should see a white box with ritpmos\_12\_pads written inside it. Type flatten and select, OK. Press F2 to unselect all.



# *MEBES - Manufacturing Electron Beam Exposure System*



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Microelectronic Engineering*

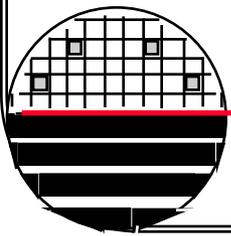
## Maskmaking Tool

## *FILE FORMATS*

Mentor- ICGraph files (filename.iccel), all layers, polygons with up to 200 vertices

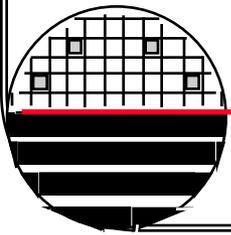
GDS2- CALMA files (old IC design tool) (filename.gds), all layers, polygons

MEBES- files for electron beam maskmaking tool, each file one layer, trapezoids only



## REFERENCES

1. Principles of CMOS VLSI Design, 2nd Ed., Neil H.E. Weste, Kmrn Eshraghian, Addison Wesley, 1993.
2. Physical Design Automation of VLSI Systems, Bryan Preas, Michael Lorenzetti, Benjamin/Cummings, 1988.
3. VLSI Engineering, Thomas Dillinger, Prentice Hall, 1988.

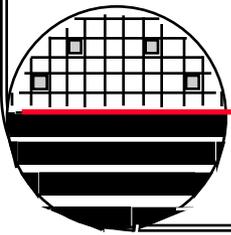


## *HOMWORK VLSI-CAD*

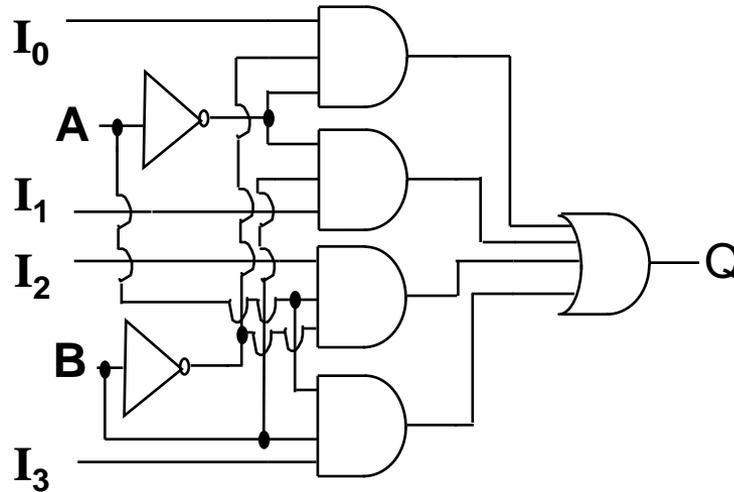
This assignment can be done using the tools in the VLSI lab. Ideally the switch level simulation and SPICE simulations are also done with the tools in the VLSI Lab.

Design a 4 to 1 multiplexer. Two inputs (Input A and Input B) select which one of four other digital inputs (I1 I2 I3 I4) is output (Vout)

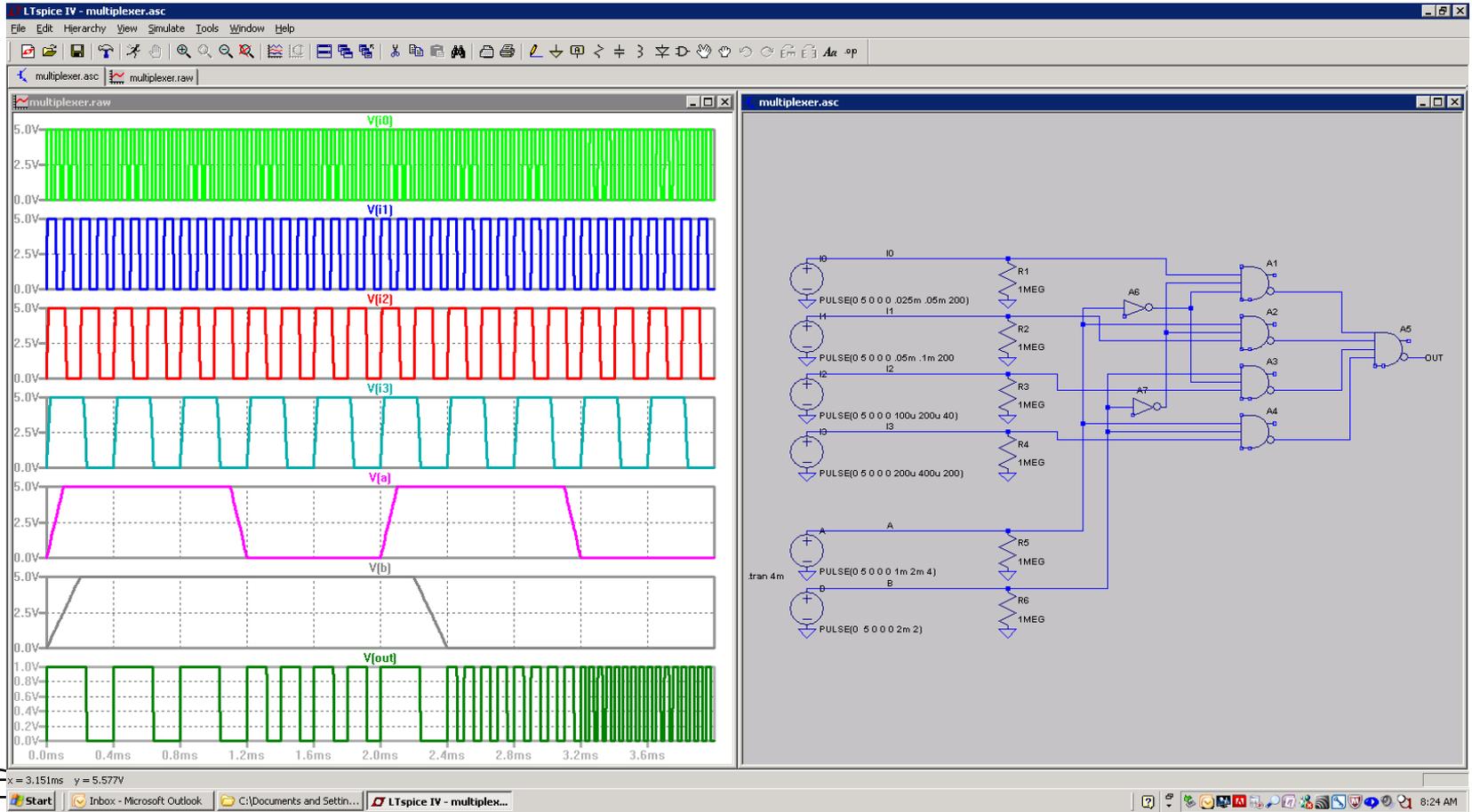
Document the following items, Truth Table, Gate Level Schematic, Gate Level Simulation, Transistor Level Schematic, Transistor Level Simulation, Layout using Gate Array, Including connections to 12-pad Pad Frame.



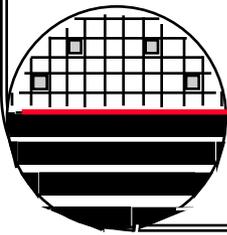
# 4 TO 1 MULTIPLEXER



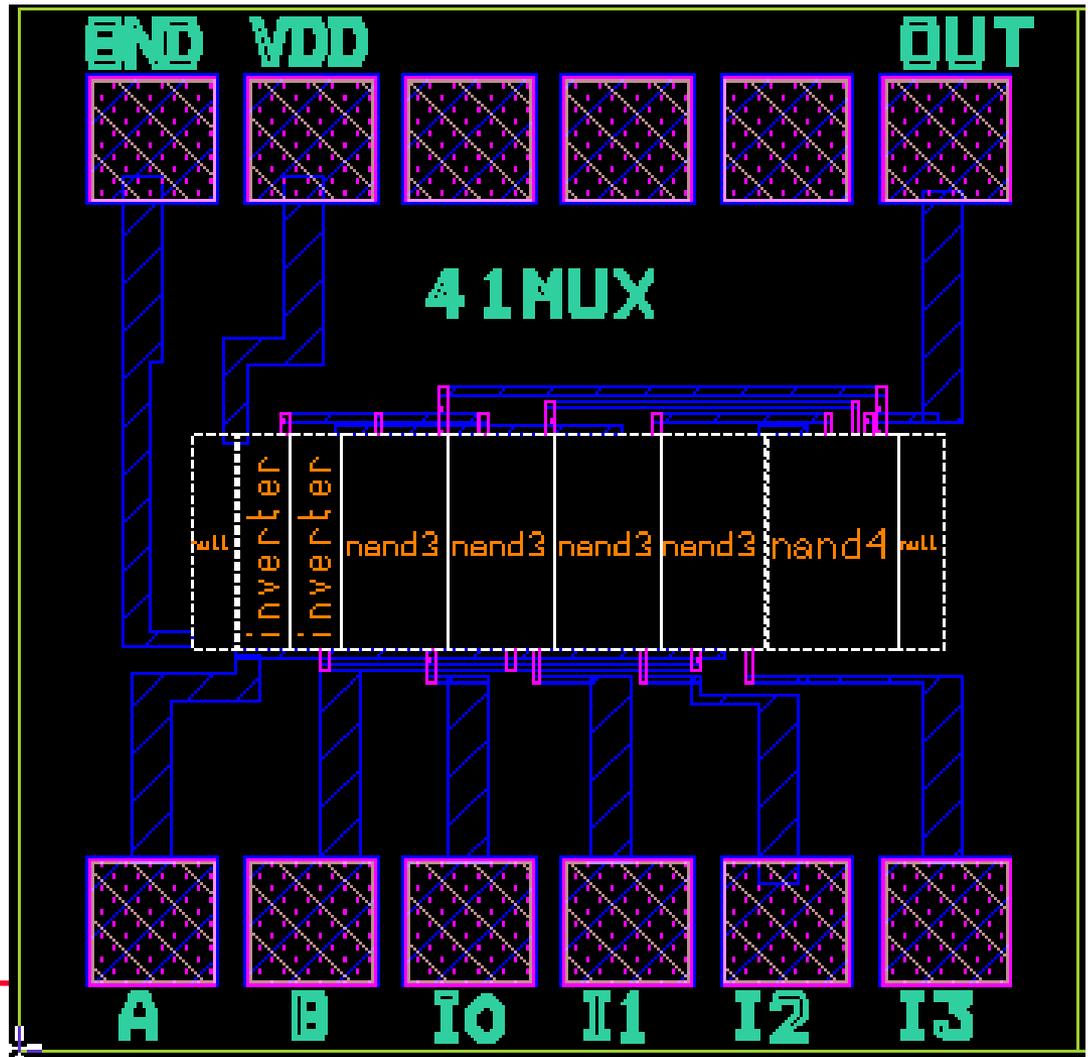
# 4 TO 1 MUX - GATE LEVEL SIMULATION



***4 TO 1 MUX – TRANSISTOR LEVEL SIMULATION***



# 4 TO 1 MUX – LAYOUT



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# 4 TO 1 MUX – PEEKED AND ZOOM

